

### N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)			
100	0.115 at V <sub>GS</sub> = 10 V	15			
	0.120 at $V_{GS}$ = 6 V	15			

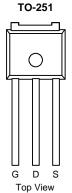
### FEATURES

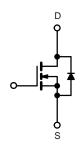
- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- 100 % R<sub>g</sub> Tested

### **APPLICATIONS**

• Primary Side Switch







N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	100		
Gate-Source Voltage	V <sub>GS</sub>	± 20	- V		
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C	1	15		
	T <sub>C</sub> = 125 °C	I <sub>D</sub>	8.7		
Pulsed Drain Current	I <sub>DM</sub>	45	A		
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	15			
Avalanche Current	I <sub>AR</sub>	15	1		
Repetitive Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AR</sub>	11.3	mJ	
Mariana Davia Diasia atian	T <sub>C</sub> = 25 °C	P <sub>D</sub>	61 <sup>b</sup>	W	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	טי	2.7 <sup>a</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
hunstien te Ambienta	t ≤ 10 s	R <sub>thJA</sub>	16	20	°C/W		
Junction-to-Ambient <sup>a</sup>	Steady State		45	55			
Junction-to-Case		R <sub>thJC</sub>	2	2.4			

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.

Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static	Cymbol			Typ.	mux.	Unit	
Drain-Source Breakdown Voltage V <sub>DS</sub>		V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 µA	100				
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$			3.0	- V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	15			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A		0.110	o		
- ·	Р	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 125 °C		0.170		Ω	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 175 °C		0.230			
		V <sub>GS</sub> = 6 V, I <sub>D</sub> = 10 A		0.115			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A		25		S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			892		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz$		110			
Reverse Transfer Capacitance	C <sub>rss</sub>			70			
Total Gate Charge <sup>c</sup>	Qg			20	25		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 75 V, $V_{GS}$ = 10 V, $I_{D}$ = 15 A		5.5		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			7			
Gate Resistance	Rg		1		3.2	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	12		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 75 V, $R_L$ = 5 $\Omega$		35	55	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ 15 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{G}$ = 2.5 $\Omega$		17	25		
Fall Time <sup>c</sup>	t <sub>f</sub>	]		30	45		
Source-Drain Diode Ratings and Cha	racteristic (T	<sub>C</sub> = 25 °C)		·			
Pulsed Current	I <sub>SM</sub>				45	Α	
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	I <sub>F</sub> = 15 A, V <sub>GS</sub> = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 15 A, dl/dt = 100 A/μs		55	85	ns	

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Notes:

a. Guaranteed by design, not subject to production testing.

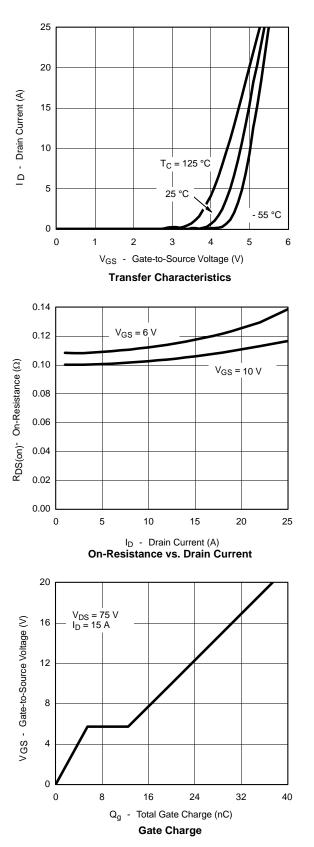
b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

 $V_{GS} = 10$  thru 5V I D - Drain Current (A) 4V 3 V V<sub>DS</sub> - Drain-to-Source Voltage (V) **Output Characteristics** T<sub>C</sub> = - 55 °C 25 °C g fs - Transconductance (S) 125 °C I<sub>D</sub> - Drain Current (A) Transconductance C - Capacitance (pF) Ciss Crss Coss V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance

#### TYPICAL CHARACTERISTICS (25 °C unless noted)



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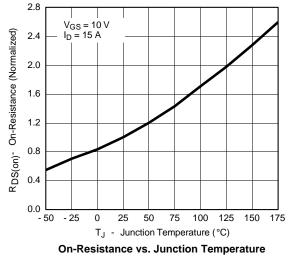
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#### TYPICAL CHARACTERISTICS (25 °C unless noted)



**THERMAL RATINGS** 

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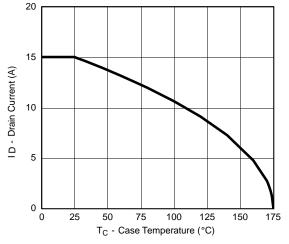
1

0.1

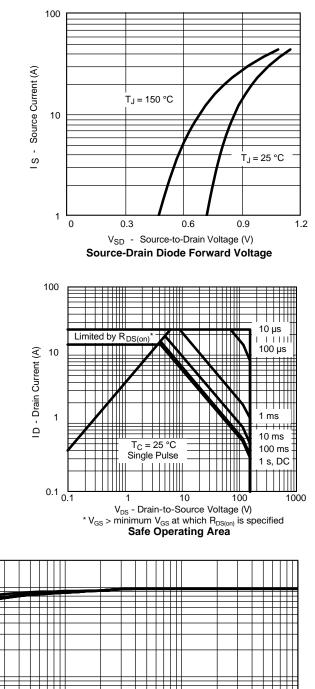
Duty Cycle = 0.5

0.02

0.2 0.1



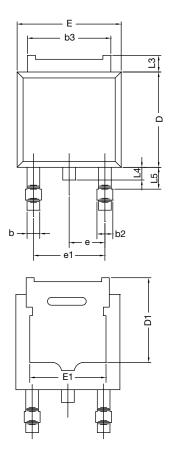
**Maximum Avalanche Drain Current** vs. Case Temperature



Normalized Effective Transient Thermal Impedance 0.05 ιТ Single Pulse 0.01 10-4 10<sup>-3</sup> 10-2 10<sup>-1</sup> 1 Square Wave Pulse Duration (sec) Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-252AA CASE OUTLINE**





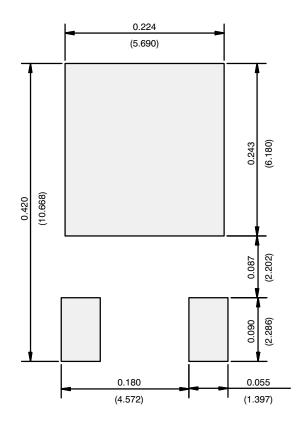
	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28 BSC		0.090	BSC	
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347					

#### Note

• Dimension L3 is for reference only.



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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